

## Renesas RA Family

# EK-RA4M1 Example Project Bundle

## Introduction

This document describes the contents of the Example Project Bundle for the EK-RA4M1 kit. The Example Projects contained within the bundle show how to write code for the various Renesas Flexible Software Package (FSP) modules supported by the EK-RA4M1 kit.

Flexible Software Package is an optimized software package designed to provide easy to use, scalable, high quality software for embedded system design. The primary goal is to provide lightweight, efficient drivers that meet common use cases in embedded systems. FSP code quality is enforced by peer reviews, automated requirements-based testing, and automated static analysis. FSP provides uniform and intuitive APIs that are well documented. Each module is supported with detailed user documentation including example code. FSP modules can be used on any MCU in the RA family, provided the MCU has any peripherals required by the module. FSP modules can be configured at build-time to optimize the size of the module for the feature set required by the application.

## Supported Kit

EK-RA4M1

## Supported FSP Version

FSP v3.4.0 or later

## Supported Toolchains

- e<sup>2</sup> studio Integrated Development Environment (IDE), default toolchain is GCC Arm Embedded
- Keil MDK with Arm compiler toolchain
- IAR EWARM with IAR toolchain for Arm

## 1. Using the Example Projects

To use EK-RA4M1 Example Projects follow the steps mentioned in the following documents:

- Example Project Usage Guide  
[https://github.com/renesas/ra-fsp-examples/blob/master/example\\_projects/Example%20Project%20Usage%20Guide.pdf](https://github.com/renesas/ra-fsp-examples/blob/master/example_projects/Example%20Project%20Usage%20Guide.pdf)
- e<sup>2</sup> studio AC6 porting Guide  
<https://en-support.renesas.com/knowledgeBase/19375553>

Users that are new to the FSP are recommended to refer to the section **Starting Development > Tutorial: Your First RA MCU Project – Blinky** in the [RA FSP Documentation](#) prior to attempting to debug an example project.

## 2. List of Example Projects Supported on Different Toolchains in the Bundle

EK-RA4M1 Example Projects	e <sup>2</sup> studio/GCC	e <sup>2</sup> studio/AC6	Keil MDK	IAR
acmplp	Supported	Supported via port from GCC		
adc	Supported	Supported via port from GCC		
adc_gpt_periodic_samplng	Supported	Supported via port from GCC		
agt	Supported	Supported via port from GCC	Supported	Supported
cac	Supported	Supported via port from GCC		
can	Supported	Supported via port from GCC		

<b>EK-RA4M1 Example Projects</b>	<b>e<sup>2</sup> studio/GCC</b>	<b>e<sup>2</sup> studio/AC6</b>	<b>Keil MDK</b>	<b>IAR</b>
cpp	Supported	Supported via port from GCC		
crc	Supported	Supported via port from GCC		
dac	Supported	Supported via port from GCC		
dmac	Supported	Supported via port from GCC	Supported	Supported
doc	Supported	Supported via port from GCC		
elc	Supported	Supported via port from GCC		
flash_lp	Supported	Supported via port from GCC	Supported	Supported
freertos	Supported	Supported via port from GCC	Supported	Supported
gpt	Supported	Supported via port from GCC	Supported	Supported
gpt_input_capture	Supported	Supported via port from GCC		
icu	Supported	Supported via port from GCC	Supported	Supported
iic_master	Supported	Supported via port from GCC		
iic_slave	Supported	Supported via port from GCC	Supported	Supported
iwdt	Supported	Supported via port from GCC		
kint	Supported	Supported via port from GCC		
lpm	Supported	Supported via port from GCC		
lvd	Supported	Supported via port from GCC		
mbed_crypto	Supported	Supported via port from GCC		
opamp	Supported	Supported via port from GCC		
_quickstart	Supported	Supported via port from GCC		
rtc	Supported	Supported via port from GCC	Supported	Supported
sci_i2c	Supported	Supported via port from GCC		
sci_spi	Supported	Supported via port from GCC		
sci_uart	Supported	Supported via port from GCC	Supported	Supported
slcdc	Supported	Supported via port from GCC		
spi	Supported	Supported via port from GCC	Supported	Supported
ssi	Supported	Supported via port from GCC		
usb_pcdc	Supported	Supported via port from GCC		
usb_phid	Supported	Supported via port from GCC		
usb_pvnd	Supported	Supported via port from GCC		
vee_flash	Supported	Supported via port from GCC		
wdt	Supported	Supported via port from GCC	Supported	Supported

**Note:** Additional example projects other than those mentioned above, maybe available in the example project bundle. However, they are supported only with older versions of FSP due to technical issues found during regression testing with the latest version.

**Website and Support**

Visit the following URLs to learn about key elements of the RA family, download components and related documentation, and get support.

RA Product Information	<a href="http://www.renesas.com/ra">www.renesas.com/ra</a>
RA Product Support Forum	<a href="http://www.renesas.com/ra/forum">www.renesas.com/ra/forum</a>
RA Flexible Software Package	<a href="http://www.renesas.com/FSP">www.renesas.com/FSP</a>
Renesas Support	<a href="http://www.renesas.com/support">www.renesas.com/support</a>

**Revision History**

Rev.	Date	Description	
		Page	Summary
1.00	Apr.23.20	—	First release document.
1.01	Jun.01.20	—	Examples updated for IAR support.
1.02	Jul.09.20	—	Updated for FSP v1.2.0.
1.03	Jul.23.20	—	Updated to add new EPs supported in FSP v1.2.0.
1.04	Aug.12.20	NA	Package updated to include this document.
1.05	Sep.03.20	—	Updated for FSP v1.3.0.
1.06	Sep.14.20	—	This revision includes changes to the code files. There are no changes to this document.
1.07	Oct.12.20	—	Added support for FSP v2.0.0.
1.08	Oct.23.20	—	Updated support for IAR and Keil, VEEPROM added.
1.09	Nov.02.20	—	Added support for FSP v2.1.0.
1.10	Dec.01.20	—	Added support for FSP v2.2.0.
1.11	Feb.02.21	—	Added support for FSP v2.3.0.
1.12	Mar.10.21	—	Added support for USB PVND.
1.13	Apr.06.21	—	Added support for FSP v2.4.0.
1.14	May.03.21	—	Added support for FSP v3.0.0.
1.15	May.13.21	—	Added support for FSP v3.0.0 (2).
1.16	Jun.16.21	—	Added support for FSP v3.0.0 (4).
1.17	Jul.12.21	—	Added support for FSP v3.1.0 (1).
1.18	Jul.26.21	—	Added support for FSP v3.1.0 (2).
1.19	Aug.30.21	—	Added support for FSP v3.1.0 (3).
1.20	Sep.10.21	—	Added support for FSP v3.2.0.
1.21	Sep.29.21	—	Added support for FSP v3.3.0 (2).
1.22	Oct.20.21	—	Added support for FSP v3.4.0 (2).

## Notice

1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
2. Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
4. You shall be responsible for determining what licenses are required from any third parties, and obtaining such licenses for the lawful import, export, manufacture, sales, utilization, distribution or other disposal of any products incorporating Renesas Electronics products, if required.
5. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
6. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.

"Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.

"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.

Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.
7. No semiconductor product is absolutely secure. Notwithstanding any security measures or features that may be implemented in Renesas Electronics hardware or software products, Renesas Electronics shall have absolutely no liability arising out of any vulnerability or security breach, including but not limited to any unauthorized access to or use of a Renesas Electronics product or a system that uses a Renesas Electronics product. RENESAS ELECTRONICS DOES NOT WARRANT OR GUARANTEE THAT RENESAS ELECTRONICS PRODUCTS, OR ANY SYSTEMS CREATED USING RENESAS ELECTRONICS PRODUCTS WILL BE INVULNERABLE OR FREE FROM CORRUPTION, ATTACK, VIRUSES, INTERFERENCE, HACKING, DATA LOSS OR THEFT, OR OTHER SECURITY INTRUSION ("Vulnerability Issues"). RENESAS ELECTRONICS DISCLAIMS ANY AND ALL RESPONSIBILITY OR LIABILITY ARISING FROM OR RELATED TO ANY VULNERABILITY ISSUES. FURTHERMORE, TO THE EXTENT PERMITTED BY APPLICABLE LAW, RENESAS ELECTRONICS DISCLAIMS ANY AND ALL WARRANTIES, EXPRESS OR IMPLIED, WITH RESPECT TO THIS DOCUMENT AND ANY RELATED OR ACCOMPANYING SOFTWARE OR HARDWARE, INCLUDING BUT NOT LIMITED TO THE IMPLIED WARRANTIES OF MERCHANTABILITY, OR FITNESS FOR A PARTICULAR PURPOSE.
8. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
12. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
13. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
14. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.

(Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.

(Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Rev.5.0-1 October 2020)

## Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,  
Koto-ku, Tokyo 135-0061, Japan  
[www.renesas.com](http://www.renesas.com)

## Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

## Contact information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:  
[www.renesas.com/contact/](http://www.renesas.com/contact/)